

Reliability, Testing, And Characterization Of MEMSMOEMS: 22-24 October 2001, San Francisco, USA

by Rajeshuni Ramesham Semiconductor Equipment and Materials International Society of Photo-optical Instrumentation Engineers

Richard S. Mullers Patents List - Berkeley Sensor & Actuator Center Reliability, Testing, and Characterization of MEMS/MOEMS II . SAES Getters/USA, Inc.; Theresa Maudie, Motorola Corp.; Juergen Mueller, Jet Propulsion. solders in MEMS packaging (Invited Paper), G. S. Selvaduray, San Jose State Univ. the International Society for Optical Engineering ; cooperating . 2006 Reliability, testing, and characterization of MEMS/MOEMS [Texte imprimé] : 22-24 October 2001, San Francisco, USA / Rajeshuni Ramesham, chair/editor . Advance Technical Program - SPIE Publication title: Reliability, testing, and characterization of MEMS/MOEMS : 22-24 October 2001, San Francisco, USA; Title of ser.: Proceedings of SPIE - the 22-24 October 2001, San Francisco, USA / Rajeshuni Ramesham . DESTIN: A new approach to interconnect reliability testing Thin-Film Silicon Science and Technology , 2009, San Francisco, CA USA, Apr 13 2009.. Testing, and Characterization of MEMS/MOEMS IV, San Jose, USA, Jan 24-25 2005. , pp.. Technology VII Conference, San Fransisco, USA, Oct 22-24, 2001. , pp. Ann Witvrouw – Department of Mechanical Engineering (MECH) IEEE Std. 1149.1-2001, IEEE Standard Test Access Port and Boundary Scan Design Automation Conference, July 24-28, 2006, San Francisco, CA, USA.. of test: design, characterization, production, October 16-18, 1984, Philadelphia, PA.. The Theory and Practice of Reliable System Design, Third Edition, AK Peters, Reliability, testing, and characterization of MEMS/MOEMS : 22-24 . Reliability, testing, and characterization of MEMS/MOEMS : 22-24 October 2001, San Francisco [Calif.], USA(Book) 12 editions published in 2001 in English Design for reliability of MEMS/MOEMS for lightwave . 8 Feb 2017 . 26th Electronic Components Conference, San Francisco, CA, April 26-28, 1976. 15. 39th Electronic Components Conference, May 22-24, 1989, Houston, TX.. IEMT Symposium, Proceedings, October 14-16, 1996, Austin, TX SPIE: Reliability, Testing, and Characterization of MEMS/MOEMS (Volume Christian A. Zorman - Advanced Platform Technology Center

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